

Fabrication Notes:

1. All dimensions in inches unless noted otherwise.
2. All materials: laminates, resins, metallizations and soldermask to be compliant with RoHS and WEEE directives.
3. Use 370 HR FR-4 or similar grade glass epoxy.
4. Tg > 145 degrees C, glass transition temperature.
5. TD > 350 degrees C, thermal decomposition.
6. Minimum flammibility rating UL94V-0, maximum dissipation factor 0.025.
7. Adjust prepreg for 0.032 , +/- 0.003 finished thickness measured over soldermask.
8. Copper thickness 0.0014 , (1 oz).
9. Hole size tolerance = +/- 0.003 unless noted otherwise.
10. Hole centers and pad centers to be concentric within 0.002 .
11. Drill chart dimensions are finished hole sizes.
12. Finish - immersion gold over nickel. No exposed bare copper permitted.
13. Solder mask over bare copper, LPI clas 2 gen. industrial registration +/- 0.004.
14. No coverage on solder pads permitted.
15. Refer to soldermask gerbers for tenting of vias.
16. White silkscreen legend over green soldermask - both sides.
17. Manufacturer icons not permitted on the silkscreen top layer.
18. PCB serialization/panel placement ID on silkscreen bottom.
19. Full electrical test against IPC-356A netlist.

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,036mm		
4	Dielectric 1	FR-4	0,908mm	4,48	
5	Bottom Layer	Copper	0,036mm		
6	Bottom Solder	Solder Resist	0,010mm	3,5	
7	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Pad Shape
□	490	0.250mm	PTH	Round	Top Layer - Bottom Layer	Rounded
○	3	0.750mm	PTH	Round	Top Layer - Bottom Layer	Rounded
☆	2	1.000mm	PTH	Round	Top Layer - Bottom Layer	Rounded
	495 Total					



















